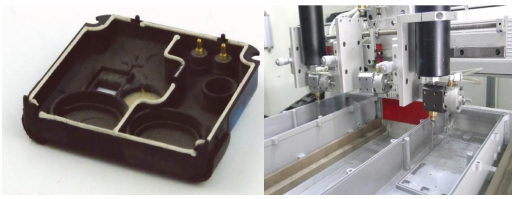
KLEBER

NYS-CURE® SG-701 Ultra Soft Non-conductive FIP Gasket



NYS-CURE® SG-701 is a single, non-slump, high flexibility, room temperature cure, silicone gasket material designed for sealing. Material is applied onto substrate by using Kleber Form-In-Place dispenser, which is an automated programmable system for dispensing non-conductive and/or conductive elastomer EMI shielding and grounding gaskets.

NYS-CURE® SG-701 has low hardness, good elasticity and low compression set. It can be bonded onto metal & plastic surface with good adhesive force. So it is quite ideal for telecom base stations, PDAs, radios, handheld terminal and consumer electronic products.

SPECIFICATIONS

Typical Performance	NYS-CURE®SG-701	Unit	Test Method
Color	White	-	Visual
Resin System	Single component Silicone	-	-
Hardness	25	Shore A	ASTM D2240
Density	1.2	g/cm^3	ASTM D792
Compression Set	<20	%	ASTM D395
Adhesion Strength	>10	N/cm	QA-WI-054
Tensile Strength	4.5	MPa	ASTM D412
Curing Mechanism	Moisture	-	-
Curing Condition	25	℃	-
Curing Time	12	H	-
Storage Condition	-30℃~-10℃, 3 Months	-	-

FEATURES & BENEFITS

- Excellent sealing properties.
- Good elasticity & ultra-soft.
- Good mechanical properties.
- Superior adhesion strength.
- Strong reliability in low compression sets.
- Heat & humidity resistance.

Declare
The recommendation and data furnished by Kleber is based on our experiment and experience to date.This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application.Kleber shall not be liable for their usage and processing. The technology data sheet is subject to change without notice. The final interpretation right of the contents of this specification belongs to Kleber.